

TOSHIBA RECTIFIER SILICON DIFFUSED TYPE

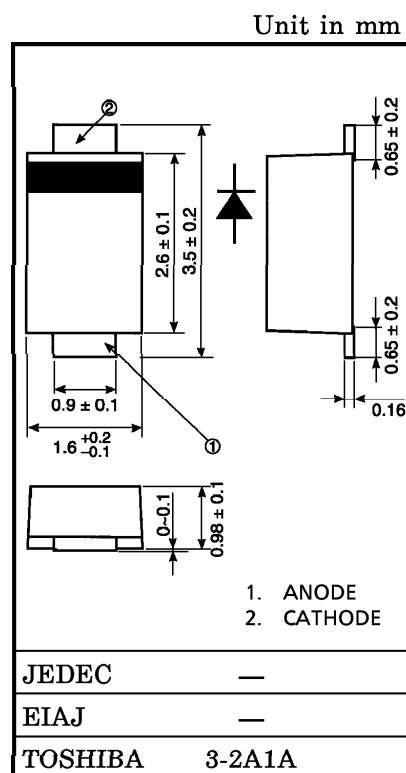
CRG01, CRG02

GENERAL PURPOSE RECTIFIER APPLICATIONS

- Average Forward Current : $I_F(AV)=0.7A$
- Repetitive Peak Reverse Voltage : $V_{RRM}=100, 400V$
- Small Package : "S-FLAT" (Toshiba designation)

MAXIMUM RATINGS

CHARACTERISTIC		SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	CRG01	V_{RRM}	100	V
	CRG02		400	
Average Forward Current		$I_F(AV)$	0.7	A
Peak One Cycle Surge Forward Current (Non-Repetitive)		I_{FSM}	15 (50Hz)	A
			16.5 (60Hz)	
Junction Temperature		T_j	-40~150	°C
Storage Temperature Range		T_{stg}	-40~150	°C



Weight : 0.013g

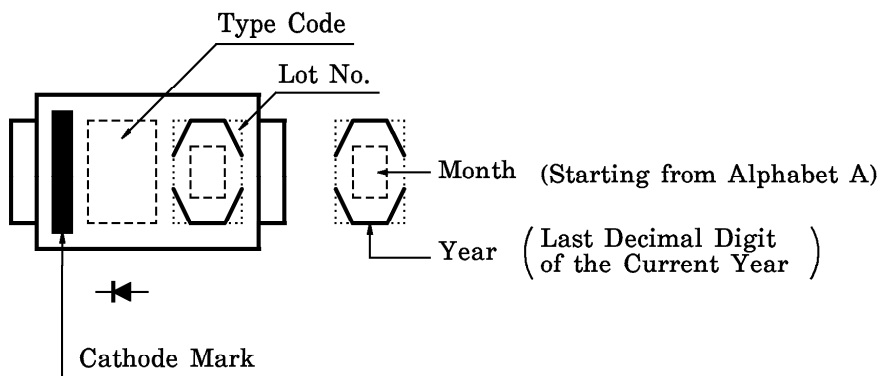
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	TYP.	MAX.	UNIT
Peak Forward Voltage	$V_{FM}(1)$	$I_{FM}=0.1A$	0.88	—	V
	$V_{FM}(2)$	$I_{FM}=0.7A$	—	1.1	
	$V_{FM}(3)$	$I_{FM}=1.0A$	1.10	—	
Repetitive Peak Reverse Current	I_{RRM}	$V_{RRM} = \text{Rated}$	—	10	μA
Thermal Resistance	$r_{th}(j-a)$ (DC)	On ceramic substrate	—	65	°C/W
		On glass-epoxy substrate	—	130	

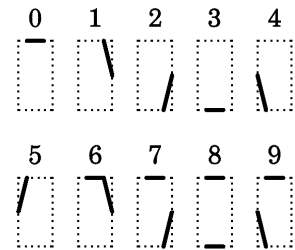
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MARKING



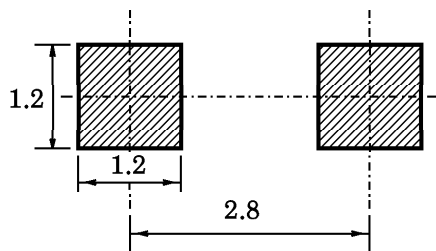
FOLLOWING INDICATES THE DATE OF MANUFACTURE

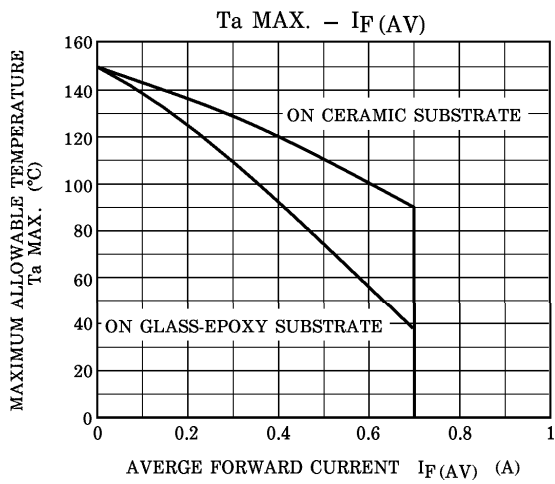
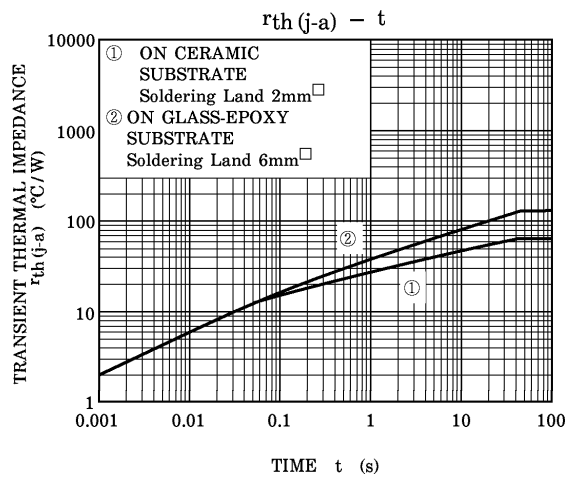
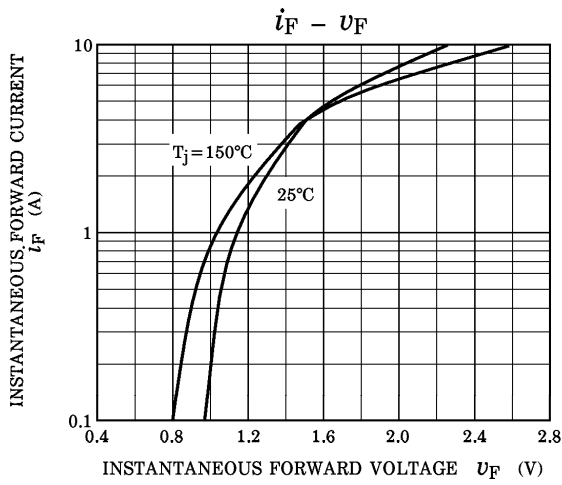


TYPE	CODE
CRG01	G1
CRG02	G2

STANDARD SOLDERING PAD

Unit : mm





	ON CERAMIC SUBSTRATE	ON GLASS-EPOXY SUBSTRATE
Soldering Land	2mm [□]	6mm [□]
Substrate Size	50mm [□]	50mm [□]
Substrate Thickness	0.64t	1.6t

